

# 2SK3418

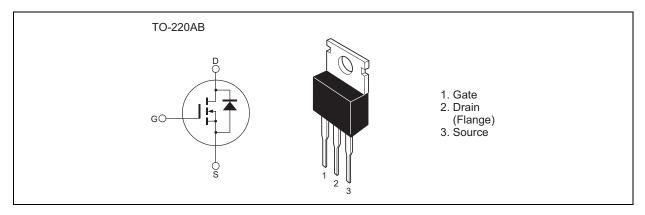
# Silicon N Channel MOS FET High Speed Power Switching

REJ03G0407-0200 (Previous ADE-208-941 (Z)) Rev.2.00 Sep.10.2004

#### **Features**

- Low on-resistance  $R_{DS(on)} = 4.3 \text{ m}\Omega \text{ typ.}$
- Capable of 4 V gate drive
- High speed switching

#### **Outline**



# **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Ratings	Unit
Drain to source voltage	$V_{DSS}$	60	V
Gate to source voltage	$V_{GSS}$	±20	V
Drain current	I <sub>D</sub>	85	Α
Drain peak current	I <sub>D</sub> (pulse) <sup>Note1</sup>	340	Α
Body-drain diode reverse drain current	I <sub>DR</sub>	85	Α
Avalanche current	I <sub>AP</sub> Note3	60	Α
Avalanche energy	E <sub>AR</sub> Note3	308	mJ
Channel dissipation	Pch <sup>Note2</sup>	110	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	– 55 to +150	°C

Notes: 1.  $PW \le 10\mu s$ , duty cycle  $\le 1\%$ 

- 2. Value at Tc = 25°C
- 3. Value at Tch = 25°C, Rg  $\geq$  50  $\Omega$

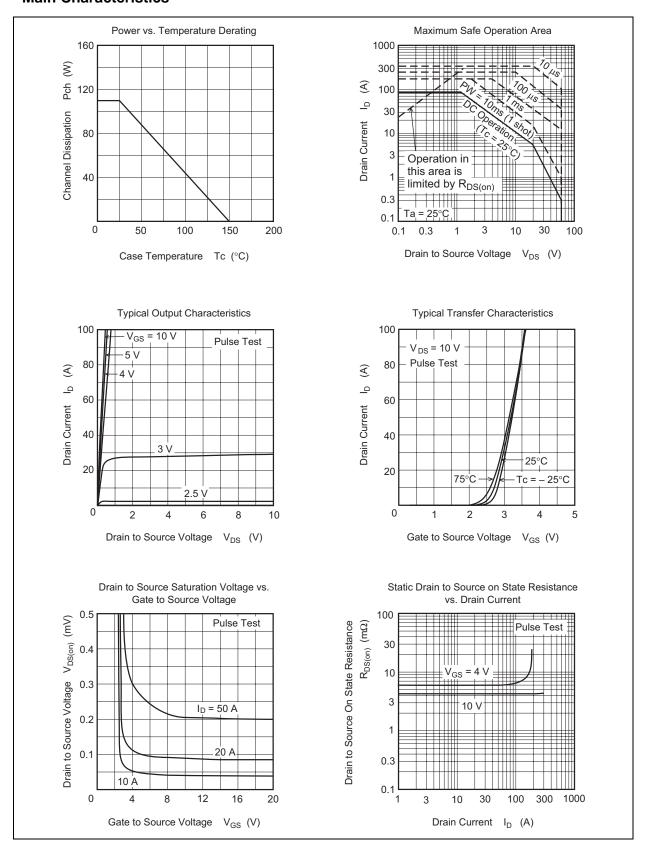
# **Electrical Characteristics**

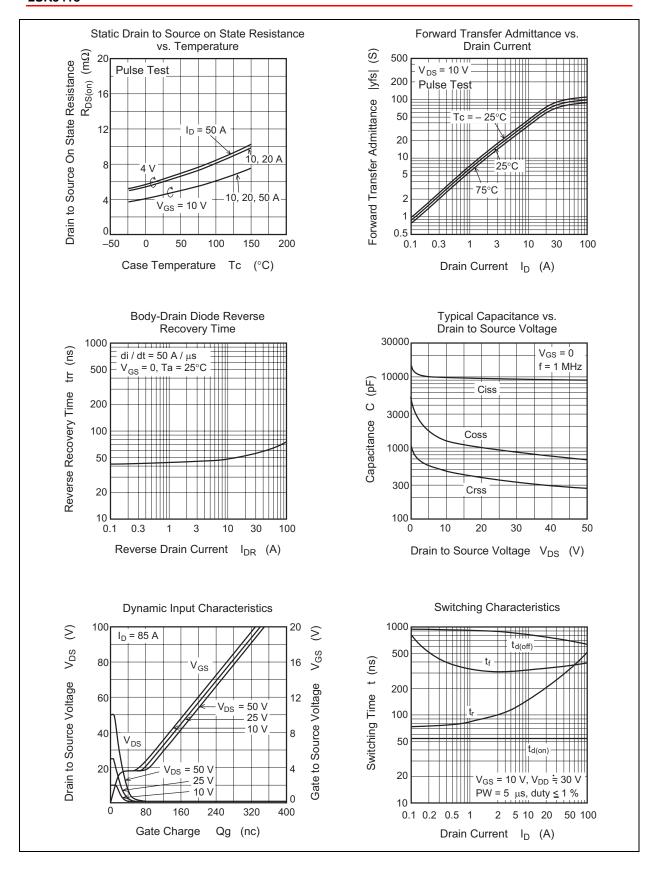
 $(Ta = 25^{\circ}C)$ 

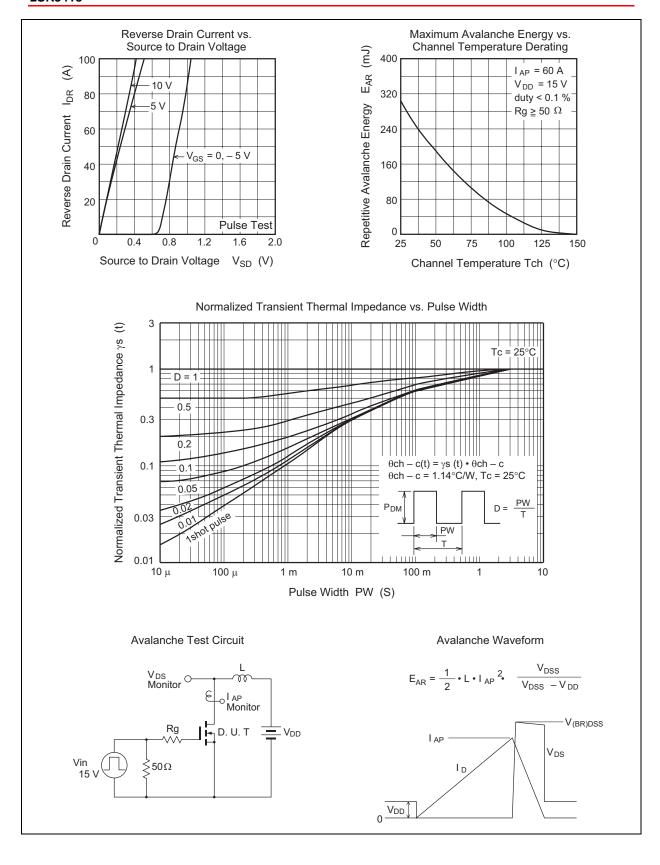
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	60	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Zero gate voltage drain current	I <sub>DSS</sub>	_	_	10	μΑ	$V_{DS} = 60 \text{ V}, V_{GS} = 0$
Gate to source leak current	I <sub>GSS</sub>	_	_	±0.1	μΑ	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	1.0	_	2.5	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}^{Note1}$
Forward transfer admittance	y <sub>fs</sub>	55	90	_	S	$I_D = 45 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note1}}$
Static drain to source on state	R <sub>DS(on)</sub>	_	4.3	5.5	mΩ	$I_D = 45 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note1}}$
resistance	R <sub>DS(on)</sub>	_	6.0	9.0	mΩ	$I_D = 45 \text{ A}, V_{GS} = 4 \text{ V}^{\text{Note1}}$
Input capacitance	Ciss	_	9770	_	pF	V <sub>DS</sub> = 10 V
Output capacitance	Coss	_	1340	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss		470	_	pF	f = 1 MHz
Total gate charge	Qg	_	180	_	nC	$V_{DD} = 50 \text{ V}$
Gate to source charge	Qgs	_	32	_	nC	$V_{GS} = 10 \text{ V}$
Gate to drain charge	Qgd	_	36	_	nC	I <sub>D</sub> = 85 A
Turn-on delay time	t <sub>d(on)</sub>	_	53	_	ns	V <sub>GS</sub> = 10 V
Rise time	t <sub>r</sub>	_	320	_	ns	I <sub>D</sub> = 45 A
Turn-off delay time	t <sub>d(off)</sub>	_	700	_	ns	$R_L = 0.67 \Omega$
Fall time	t <sub>f</sub>	_	380	_	ns	
Body-drain diode forward voltage	$V_{DF}$	_	1.0	_	V	$I_F = 85 \text{ A}, V_{GS} = 0$
Body-drain diode reverse recovery time	t <sub>rr</sub>	_	70	_	ns	$I_F = 85 \text{ A}, V_{GS} = 0$ diF / dt = 50 A / $\mu$ s

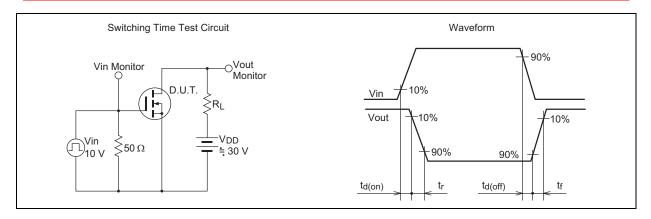
Note: 1. Pulse test

# **Main Characteristics**

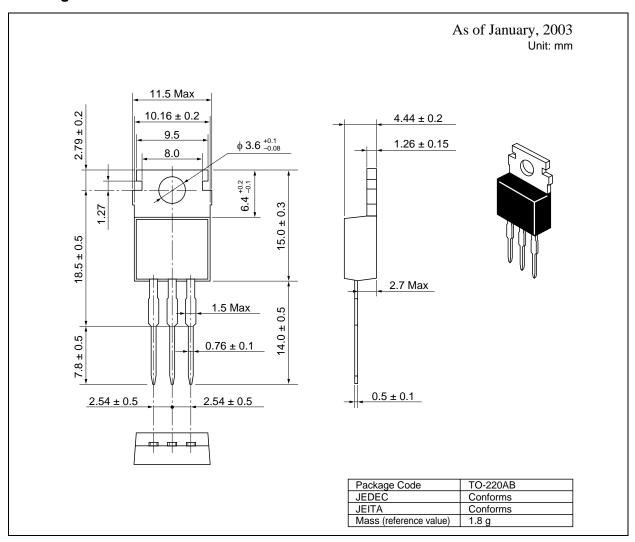








# **Package Dimensions**



# **Ordering Information**

Part Name	Quantity	Shipping Container
2SK3418-E	50 pcs	sack

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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